

1 **ABSTRACT OF THE DISCLOSURE**

2 A semiconductor processor for spray coating wafers or other
3 semiconductor articles. The processor has a compartment in which are
4 mounted a wafer transfer, coating station and thermal treatment station.
5 The coating station has a spray processing vessel in which a movable
6 spray-head and rotatable wafer holder. The spray station has coating
7 viscosity control features. An ultrasonic resonating spray-head is
8 precisely supplied with coating from a metering pump. The heat
9 treatment station heat cures the coating and then cools the wafer. The
10 system allows coatings to be applied in relatively uniform conformational
11 layers upon irregular surfaces.

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